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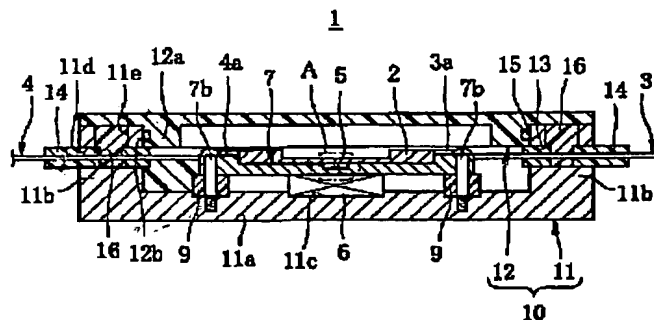
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APPLICANT : FURUKAWA ELECTRIC CO LTD:THE;

INVENTOR : SAITO TSUNEAKI;

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TITLE : OPTICAL WAVEGUIDE MODULE



ABSTRACT : PROBLEM TO BE SOLVED: To provide a compact optical waveguide module allowed to be stably used over a long period even in an environment of high temperature and high humidity and to be easily assembled at the time of its manufacture by sealing the inside and outside of a package to prevent the generation of dew condensation on an optical waveguide component.

SOLUTION: In the optical waveguide module 1, at least a plane type optical waveguide component 2, a temperature sensor 5 for detecting the temperature of the component 2 and a temperature control element 6 for controlling the temperature of the component at a prescribed temperature are stored in a package 10 surrounding these parts. The inside and outside of the package 10 are airtightly sealed by sealing members 15, 16.

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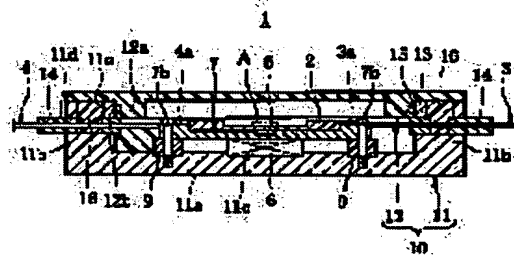
(22)Date of filing : 09.11.1998 (72)Inventor : TORATANI TOMOAKI
SAITO TSUNEAKI

(54) OPTICAL WAVEGUIDE MODULE

(57)Abstract:

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